

## INFORMATION CITED BY APPLICANTS THAT MAY BE MATERIAL TO THE PROSECUTION OF THE SUBJECT APPLICATION

Applicant:

Z. Hu et al.

Attorney Docket No. SEMT119899

Application No.: 10/667,795

Filed:

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Title:

THIOUREA- AND CYANIDE-FREE BATH AND PROCESS FOR

**ELECTROLYTIC ETCHING OF GOLD** 

## **U.S. PATENT DOCUMENTS**

*Examiner Cite Initials No.	Document No.	Kind Code	Date (mm/dd/yyyy)	Name
med UI	3,935,005	A	01/27/1976	Solidum et al.
U2	4,142,953	Α	03/06/1979	Lovelace
U3	4,144,090	Α	03/13/1979	Franz
U4	4,192,729	Α	03/11/1980	Cancelleri et al.
U5	4,208,378	Α	06/17/1980	Heinen et al.
U6	4,243,532	Α	01/06/1981	Tsuda et al.
U7	4,285,784	Α	08/25/1981	Flinn et al.
U8	4,303,482	Α	12/01/1981	Bühne et al.
U9	4,324,626	Α	04/13/1982	McGivern, Jr.
U10	4,358,352	Α	11/09/1982	Rhoda
U11	4,385,971	Α	05/31/1983	Swartz
U12	4,427,502	Α	01/24/1984	Abys
U13	4,430,178	Α	02/07/1984	Anderson et al.
U14	4,483,789	Α	11/20/1984	Kunze et al.
U15	4,750,977	Α	06/14/1988	Marrese
U16	5,096,550	Α	05/17/1992	Mayer et al.
U17	5,127,207	Α	07/07/1992	Cunningham
U18	5,221,421	Α	06/22/1993	Leibovitz et al.
U19	5,232,328	Α	08/03/1993	Owczarz et al.

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MEG	U20	5,304,359	A	04/19/1994	Duyvesteyn et al.
	U21	5,310,475	Α	05/10/1994	Kitada et al.
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	U27	5,484,518	Α	01/16/1996	Goldberg
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	U38	5,985,126	Α	11/16/1999	Blek et al.
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	U47	6,359,328	B1	03/19/2002	Dubin

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*Examiner Cite			Kind	Date	
<u>Initials</u>	No.	Document No.	Code	(mm/dd/yyyy)	Name
MIA	U48	6,491,806	B1	12/10/2002	Dubin et al.
	U49	2001/0015321	<b>A</b> 1	08/23/2001	Reid et al.
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	U51	2002/0074234	A1	06/20/2002	Dubin et al.
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## **FOREIGN PATENT DOCUMENTS**

+rs : 0':					Dublication Date	English	
	*Examiner	Cite		Kind	Publication Date		Abstract Translation
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	med	Fl	WO 98/02909	<b>A</b> 1	01/22/1998	WO	

## OTHER INFORMATION (Including Author, Title, Date, Pertinent Pages, Etc.)

*Examiner Initial	Cite No.	
mru	O1	Moffat, T.P., et al., "Superconformal Electrodeposition of Copper in 500-90 nm Features," <i>Journal of The Electrochemical Society</i> 147(12):4524-4535, 2000.
mld	O2	Moffat, T.P., et al., "Superconformal Electrodeposition of Copper," Electrochemical and Solid-State Letters 4(4):C26-C29, 2001.
mld	О3	Wheeler, D., et al., "Modeling Superconformal Electrodeposition Using the Level Set Method," <i>Journal of The Electrochemical Society</i> 150(5):C302-C310, 2003.

Examiner Malan

Date Considered

1-18-2006

\*Examiner: Initial if reference considered, whether or not citation is in conformance with M.P.E.P. § 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicants.

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